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(54) Title: A METHOD AND APPARATUS FOR BONDING TOGETHER TWO WAFERS BY MOLECULAR ADHESION

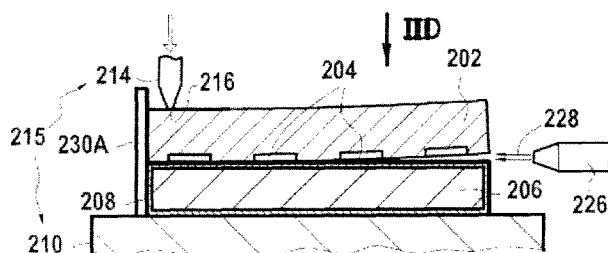


FIG. 2C

(57) Abstract: The invention provides a method of bonding a first wafer (202) onto a second wafer (206) by molecular adhesion, the method comprising applying a point of initiation (216) of a bonding wave between said first (202) and second (206) wafers, the method further comprising projecting a gas stream (228) between the first wafer (202) and the second wafer (206) generally towards the point of initiation (216) of the bonding wave while the bonding wave is propagating between the wafers. The invention also provides a bonding apparatus (215) for carrying out said bonding method.